Small Signal MOSFET 150 mAmps, 60 Volts

N-Channel TO-92

Features

• This is a Pb-Free Device*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain - Source Voltage	V _{DSS}	60	Vdc
Drain–Gate Voltage (R _{GS} = 1.0 MΩ)	V_{DGR}	60	Vdc
Gate–Source Voltage – Continuous – Non–repetitive (t _p ≤ 50 μs)	V _{GS} V _{GSM}	±20 ±40	Vdc Vpk
Drain Current - Continuous - Pulsed	I _D I _{DM}	150 1000	mAdc
Total Power Dissipation @ T _A = 25°C Derate above 25°C	P _D	400 3.2	mW mW/°C
Operating and Storage Temperature Range	T _J , T _{stg}	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	312.5	°C/W
Maximum Lead Temperature for Soldering Purposes, 1/16" from case for 10 seconds	TL	300	°C

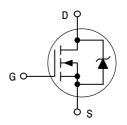


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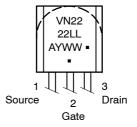
150 mA, 60 V $R_{DS(on)} = 7.5 \Omega$

N-Channel





MARKING DIAGRAM & PIN ASSIGNMENT



A = Assembly Location

Y = Year WW = Work Week ■ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

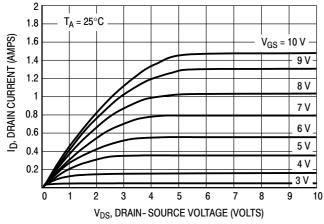
Characteris	Symbol	Min	Max	Unit	
OFF CHARACTERISTICS		-	-	-	
Drain-Source Breakdown Voltage (V _{GS} = 0, I _D = 100 µAdc)		V _{(BR)DSS}	60	-	Vdc
Zero Gate Voltage Drain Current $(V_{DS} = 48 \text{ Vdc}, V_{GS} = 0)$ $(V_{DS} = 48 \text{ Vdc}, V_{GS} = 0, T_J = 125^{\circ}\text{C})$		I _{DSS}	- -	10 500	μAdc
Gate-Body Leakage Current, Forward (V _{GSF} = 30 Vdc, V _{DS} = 0)		I _{GSSF}	-	-100	nAdc
ON CHARACTERISTICS (Note 1)			-	-	
Gate Threshold Voltage $(V_{DS} = V_{GS}, I_D = 1.0 \text{ mAdc})$		V _{GS(th)}	0.6	2.5	Vdc
Static Drain–Source On–Resistance $(V_{GS} = 10 \text{ Vdc}, I_D = 0.5 \text{ Adc})$ $(V_{GS} = 10 \text{ Vdc}, I_D = 0.5 \text{ Vdc}, T_C = 125^{\circ}\text{C})$		r _{DS(on)}	- -	7.5 13.5	Ω
Drain-Source On-Voltage ($V_{GS} = 5.0 \text{ Vdc}$, $I_D = 200 \text{ mAdc}$) ($V_{GS} = 10 \text{ Vdc}$, $I_D = 500 \text{ mAdc}$)		V _{DS(on)}	_ _	1.5 3.75	Vdc
On–State Drain Current $(V_{GS} = 10 \text{ Vdc}, V_{DS} \ge 2.0 \text{ V}_{DS(on)})$		I _{D(on)}	750	-	mA
Forward Transconductance (V _{DS} = 10 Vdc, I _D = 500 mAdc)		9 _{fs}	100	-	μmhos
DYNAMIC CHARACTERISTICS		•			•
Input Capacitance		C _{iss}	-	60	pF
Output Capacitance	$(V_{DS} = 25 \text{ Vdc}, V_{GS} = 0,$ f = 1.0 MHz)	C _{oss}	-	25	
Reverse Transfer Capacitance	1 - 1.0 1.1.2,	C _{rss}	-	5.0	
SWITCHING CHARACTERISTICS (Note 1)					
Turn-On Delay Time	(V _{DD} = 15 Vdc, I _D = 600 mA,	t _{on}	-	10	ns
Turn-Off Delay Time	$R_{gen} = 25 \Omega, R_L = 23 \Omega$	t _{off}	-	10	

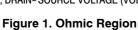
^{1.} Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.

ORDERING INFORMATION

Device	Package	Shipping [†]
VN2222LLG	TO-92 (Pb-Free)	1000 Unit / Box

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.





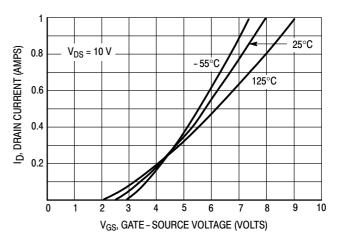
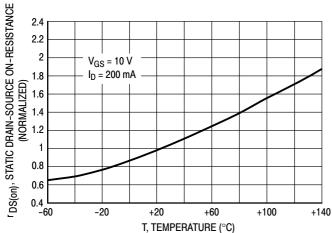
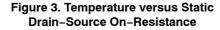


Figure 2. Transfer Characteristics





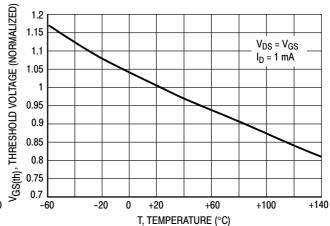
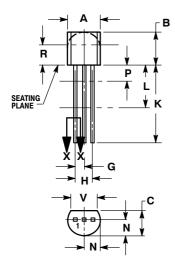


Figure 4. Temperature versus Gate Threshold Voltage

PACKAGE DIMENSIONS

TO-92 CASE 29-11 **ISSUE AM**



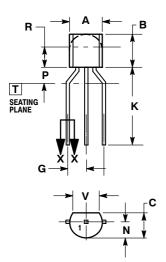
STRAIGHT LEAD **BULK PACK**



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
 CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
- LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.175	0.205	4.45	5.20
В	0.170	0.210	4.32	5.33
С	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
Н	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500		12.70	
L	0.250		6.35	
N	0.080	0.105	2.04	2.66
P		0.100		2.54
R	0.115		2.93	
٧	0.135		3.43	



BENT LEAD TAPE & REEL AMMO PACK



NOTES:

- DIMENSIONING AND TOLERANCING PER 1. ASMF Y14 5M 1994
- CONTROLLING DIMENSION: MILLIMETERS.
- CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
- LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	MILLIMETERS		
DIM	MIN	MAX	
Α	4.45	5.20	
В	4.32	5.33	
С	3.18	4.19	
D	0.40	0.54	
G	2.40	2.80	
J	0.39	0.50	
K	12.70		
N	2.04	2.66	
P	1.50	4.00	
R	2.93		
٧	3.43		

STYLE 22: PIN 1. SOURCE 2. GATE 3.

DRAIN

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